

Title (en)

Method and apparatus for applying solder to a substrate

Title (de)

Verfahren und Einrichtung zum Auftragen von Lot auf ein Substrat

Title (fr)

Méthode et appareil pour appliquer de la brazure à un substrat

Publication

**EP 1393845 B1 20060920 (DE)**

Application

**EP 03100535 A 20030305**

Priority

- EP 03100535 A 20030305
- EP 02005422 A 20020308

Abstract (en)

[origin: EP1393845A2] The method involves melting solder wire (7) in a mixing chamber (6) and feeding it into a flow of gas and moving or lowering a two medium nozzle (4) relative to the substrate (1) so as to deposit solder blown out of the nozzle onto the substrate. The solder wire is fed to the mixing chamber in a guide tube (9) and its end is retracted into the guide tube to interrupt the deposition process. AN Independent claim is also included for the following: (a) a device for applying solder to a substrate.

IPC 8 full level

**B23K 1/012** (2006.01); **B23K 3/00** (2006.01); **B23K 3/06** (2006.01)

CPC (source: EP)

**B23K 3/063** (2013.01); **B23K 2101/40** (2018.07)

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DOCDB simple family (publication)

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